

# Kazuya Masu

## List of Publications by Year in descending order

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all docs

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docs citations

221  
times ranked

1006  
citing authors

| #  | ARTICLE   | IF  | CITATIONS |
|----|---|-----|-----------|
| 1  | Complete planarization of via holes with aluminum by selective and nonselective chemical vapor deposition. Applied Physics Letters, 1990, 57, 1221-1223.  | 3.3 | 71        |
| 2  | Design of sub-1g microelectromechanical systems accelerometers. Applied Physics Letters, 2014, 104, .   | 3.3 | 64        |
| 3  | Selective aluminum chemical vapor deposition. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 1992, 10, 856-862.  | 2.1 | 55        |
| 4  | New binary sequences with zero-correlation duration for approximately synchronised CDMA. Electronics Letters, 2000, 36, 991.  | 1.0 | 54        |
| 5  | A Bidirectional- and Multi-Drop-Transmission-Line Interconnect for Multipoint-to-Multipoint On-Chip Communications. IEEE Journal of Solid-State Circuits, 2008, 43, 1020-1029.                            | 5.4 | 53        |
| 6  | Acceptor energy level for Zn in Ga $_{1-x}$ Al $_x$ As. Journal of Applied Physics, 1980, 51, 1060-1064.  | 2.5 | 48        |
| 7  | Pyrolysis and Photolysis of Trimethylaluminum. Japanese Journal of Applied Physics, 1986, 25, 1236-1242.  | 1.5 | 46        |
| 8  | On-Chip Variable Inductor Using Microelectromechanical Systems Technology. Japanese Journal of Applied Physics, 2003, 42, 2190-2192.  | 1.5 | 39        |
| 9  | Selective deposition of aluminum from selectively excited metalorganic source by the rf plasma. Applied Physics Letters, 1990, 56, 1543-1545.   | 3.3 | 38        |
| 10 | Transmission Electron Microscopic Observation of $\text{AlN}/\text{Al}_2\text{O}_3$ Heteroepitaxial Interface with Initial-Nitriding AlN Layer. Japanese Journal of Applied Physics, 1995, 34, L760-L763. | 1.5 | 38        |
| 11 | Full duplex transmission operation of a 2.45-GHz asynchronous spread spectrum using a SAN convolver. IEEE Transactions on Ultrasonics, Ferroelectrics, and Frequency Control, 1993, 40, 478-482.          | 3.0 | 33        |
| 12 | Pulse electroplating of ultra-fine grained Au films with high compressive strength. Electrochemistry Communications, 2016, 67, 51-54.   | 4.7 | 33        |
| 13 | Area-selective CVD of metals. Thin Solid Films, 1993, 228, 312-318.   | 1.8 | 32        |
| 14 | On-Chip High-Q Variable Inductor Using Wafer-Level Chip-Scale Package Technology. IEEE Transactions on Electron Devices, 2006, 53, 2401-2406.   | 3.0 | 31        |
| 15 | Alloy scattering potential in $\text{Ga}_{1-x}\text{Al}_x\text{As}$ . Journal of Applied Physics, 1983, 54, 5785-5792.  | 2.5 | 30        |
| 16 | On-chip transmission line for long global interconnects. , 0, , .   |     | 30        |
| 17 | RF-Powered Transceiver With an Energy- and Spectral-Efficient IF-Based Quadrature Backscattering Transmitter. IEEE Journal of Solid-State Circuits, 2015, 50, 2975-2987.                                  | 5.4 | 29        |
| 18 | Integrated CMOS-MEMS Technology and Its Applications. ECS Transactions, 2014, 61, 21-39.  | 0.5 | 26        |

| #  | ARTICLE   | IF  | CITATIONS |
|----|---|-----|-----------|
| 19 | Variable RF Inductor on Si CMOS Chip. Japanese Journal of Applied Physics, 2004, 43, 2293-2296.   | 1.5 | 24        |
| 20 | Novel Sensor Structure and Its Evaluation for Integrated Complementary Metal Oxide Semiconductor Microelectromechanical Systems Accelerometer. Japanese Journal of Applied Physics, 2013, 52, 06GL04.           | 1.5 | 23        |
| 21 | Area-Selective Aluminum Patterning Using Atomic Hydrogen Resist. Japanese Journal of Applied Physics, 1993, 32, 278-281.  | 1.5 | 22        |
| 22 | Fabrication and evaluation of an on-chip micro-variable inductor. Microelectronic Engineering, 2003, 67-68, 582-587.  | 2.4 | 22        |
| 23 | Differential transmission line interconnect for high speed and low power global wiring. , 0, , .  |     | 21        |
| 24 | A 0.5 V 5.96-GHz PLL With Amplitude-Regulated Current-Reuse VCO. IEEE Microwave and Wireless Components Letters, 2017, 27, 302-304.   | 3.2 | 21        |
| 25 | Wide Tuning Range LC-VCO Using Variable Inductor for Reconfigurable RF Circuit. IEICE Transactions on Fundamentals of Electronics, Communications and Computer Sciences, 2005, E88-A, 507-512.                  | 0.3 | 21        |
| 26 | Preparation of $(\text{Al}_x\text{Ga}_{1-x})\text{In}_y\text{As}$ ( $0 \leq x \leq 0.5, y=0.47$ ) lattice matched to InP substrates by molecular beam epitaxy. Journal of Applied Physics, 1982, 53, 7558-7560. | 2.5 | 20        |
| 27 | Temperature-Scaling Theory for Low-Temperature-Operated MOSFET with Deep-Submicron Channel. Japanese Journal of Applied Physics, 1988, 27, L1958-L1961.   | 1.5 | 20        |
| 28 | On-die parameter extraction from path-delay measurements. , 2009, , .   |     | 20        |
| 29 | AlN epitaxial growth on atomically flat initially nitrided $\text{Al}_2\text{O}_3$ wafer. Applied Surface Science, 1997, 117-118, 540-545.  | 6.1 | 19        |
| 30 | Low temperature deposited ZrB film applicable to extremely thin barrier for copper interconnect. Applied Surface Science, 2009, 256, 1222-1226.   | 6.1 | 19        |
| 31 | A 1.3-2.8 GHz Wide Range CMOS LC-VCO Using Variable Inductor. , 2005, , .   |     | 18        |
| 32 | Robust importance sampling for efficient SRAM yield analysis. , 2010, , .   |     | 18        |
| 33 | A Single-Platform Simulation and Design Technique for CMOS-MEMS Based on a Circuit Simulator With Hardware Description Language. Journal of Microelectromechanical Systems, 2013, 22, 755-767.                  | 2.5 | 18        |
| 34 | A dual-axis MEMS capacitive inertial sensor with high-density proof mass. Microsystem Technologies, 2016, 22, 459-464.  | 2.0 | 18        |
| 35 | Contribution of free electrons to Al CVD on a Si surface by photo-excitation. Applied Surface Science, 1994, 79-80, 237-243.  | 6.1 | 17        |
| 36 | Accurate Array-Based Measurement for Subthreshold-Current of MOS Transistors. IEEE Journal of Solid-State Circuits, 2009, 44, 2977-2986.  | 5.4 | 17        |

| #  | ARTICLE  | IF  | CITATIONS |
|----|--|-----|-----------|
| 37 | A 0.98 to 6.6 Hz Tunable Wideband VCO in a 180nm CMOS Technology for Reconfigurable Radio Transceiver. , 2006, , .   |     | 16        |
| 38 | A Variability-Aware Adaptive Test Flow for Test Quality Improvement. IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems, 2014, 33, 1056-1066.               | 2.7 | 16        |
| 39 | Reproducible diffusion of beryllium into GaAs during liquid phase epitaxial growth. Applied Physics Letters, 1980, 37, 182-184.  | 3.3 | 15        |
| 40 | 4 Gbps On-Chip Interconnection using Differential Transmission Line. , 2005, , .   |     | 15        |
| 41 | Assessment of Testicular Corticosterone Biosynthesis in Adult Male Rats. PLoS ONE, 2015, 10, e0117795.   | 2.5 | 15        |
| 42 | Epitaxial growth of AlN film by low-pressure MOCVD in gas-beam-flow reactor. Journal of Crystal Growth, 1991, 115, 643-647.  | 1.5 | 14        |
| 43 | Equivalent Circuit Analysis of RF-Integrated Inductors with/without Ferromagnetic Material. Japanese Journal of Applied Physics, 2003, 42, 2210-2213.                                  | 1.5 | 14        |
| 44 | Au-Cu Alloys Prepared by Pulse Electrodeposition toward Applications as Movable Micro-Components in Electronic Devices. Journal of the Electrochemical Society, 2018, 165, D58-D63.    | 2.9 | 14        |
| 45 | In Situ Observation of Electromigration in Cu Film Using Scanning Åu-Reflection High-Energy Electron Diffraction Microscope. Japanese Journal of Applied Physics, 1991, 30, 3642-3645. | 1.5 | 13        |
| 46 | A dynamic reconfigurable RF circuit architecture. , 2005, , .  |     | 13        |
| 47 | RF Passive Components Using Metal Line on Si CMOS. IEICE Transactions on Electronics, 2006, E89-C, 681-691.  | 0.6 | 13        |
| 48 | Precursor design and selective aluminum CVD. Vacuum, 1995, 46, 1249-1253.  | 3.5 | 12        |
| 49 | A 6.5-mW 5-Gbps On-Chip Differential Transmission Line Interconnect with a Low-Latency Asymmetric Tx in a 180nm CMOS Technology. , 2006, , .   |     | 12        |
| 50 | A Low-Latency and High-Power-Efficient On-Chip LVDS Transmission Line Interconnect for an RC Interconnect Alternative. , 2007, , .   |     | 12        |
| 51 | An Adaptive Test for Parametric Faults Based on Statistical Timing Information. , 2009, , .  |     | 12        |
| 52 | 13.8 A 5.8GHz RF-powered transceiver with a 113&#x03BC;W 32-QAM transmitter employing the IF-based quadrature backscattering technique. , 2015, , .                                    |     | 12        |
| 53 | Structure stability of high aspect ratio Ti/Au two-layer cantilevers for applications in MEMS accelerometers. Microelectronic Engineering, 2016, 159, 90-93.                           | 2.4 | 12        |
| 54 | Design of CMOS inverter-based output buffers adapting the cherry-hooper broadbanding technique. , 2009, , .  |     | 11        |

| #  | ARTICLE  | IF  | CITATIONS |
|----|--|-----|-----------|
| 55 | SMAFTI packaging technology for new interconnect hierarchy. , 2009, , .  |     | 11        |
| 56 | An arrayed accelerometer device of a wide range of detection for integrated CMOS-MEMS technology. Japanese Journal of Applied Physics, 2014, 53, 027202.   | 1.5 | 11        |
| 57 | Enhancement of mechanical strength in Au films electroplated with supercritical carbon dioxide. Electrochemistry Communications, 2016, 72, 126-130.  | 4.7 | 11        |
| 58 | Tensile tests of micro-specimens composed of electroplated gold. Microelectronic Engineering, 2017, 174, 6-10.   | 2.4 | 11        |
| 59 | (Invited) CMOS-MEMS Based Microgravity Sensor and Its Application. ECS Transactions, 2020, 97, 91-108.   | 0.5 | 11        |
| 60 | The Role of Be in $(\text{GaAl})\text{As}/\text{GaAs}$ Solar Cells. Journal of the Electrochemical Society, 2002, 129, 1623-1627.  | 1.2 | 11        |
| 61 | Diffusion of beryllium into GaAs during liquid phase epitaxial growth of $\text{Ga}_{0.2}\text{Al}_{0.8}\text{As}$ . Journal of Applied Physics, 1983, 54, 1574-1578.  | 2.5 | 10        |
| 62 | Superiority of DMAH to DMEAA for al CVD technology. Materials Science in Semiconductor Processing, 1999, 2, 303-308.   | 4.0 | 10        |
| 63 | Path clustering for adaptive test. , 2010, , .   |     | 10        |
| 64 | Promoted bending strength in micro-cantilevers composed of nanograined gold toward MEMS applications. Microelectronic Engineering, 2018, 196, 20-24.   | 2.4 | 10        |
| 65 | Silicon Nitride Films with Low Hydrogen Content, Low Stress, Low Damage and Stoichiometric Composition by Photo-Assisted Plasma CVD. Japanese Journal of Applied Physics, 1989, 28, L2316-L2319.   | 1.5 | 9         |
| 66 | Atomic hydrogen resist process with electron beam lithography for selective Al patterning. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1994, 12, 3270. | 1.6 | 9         |
| 67 | Reconfigurable RF circuit design for multi-band wireless chip. , 0, , .  |     | 9         |
| 68 | RF Attenuation Characteristics for In Vivo Wireless Healthcare Chip. Japanese Journal of Applied Physics, 2005, 44, 5275-5277.   | 1.5 | 9         |
| 69 | A sub-1mw 5.5-GHz PLL with digitally-calibrated ILFD and linearized varactor for low supply voltage operation. , 2013, , .   |     | 9         |
| 70 | A 0.52-V 5.7-GHz low noise sub-sampling PLL with dynamic threshold MOSFET. , 2014, , .   |     | 9         |
| 71 | A 0.1 G-to-20 G integrated MEMS inertial sensor. Japanese Journal of Applied Physics, 2015, 54, 087202.  | 1.5 | 9         |
| 72 | High-Strength Electroplated Au-Cu Alloys as Micro-Components in MEMS Devices. Journal of the Electrochemical Society, 2017, 164, D244-D247.  | 2.9 | 9         |

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|----|--|-----|-----------|
| 73 | Distributed Sensing Via Inductively Coupled Single-Transistor Chaotic Oscillators: A New Approach and Its Experimental Proof-of-Concept. IEEE Access, 2020, 8, 36536-36555.                      | 4.2 | 9         |
| 74 | In Vivo Batteryless Wireless Communication System for Bio-MEMS Sensors. Japanese Journal of Applied Physics, 2005, 44, 2879-2882.  | 1.5 | 8         |
| 75 | Physical Modeling of MEMS Variable Inductor. IEEE Transactions on Circuits and Systems II: Express Briefs, 2008, 55, 419-422.  | 3.0 | 8         |
| 76 | An over-12-Gbps on-chip transmission line interconnect with a pre-emphasis technique in 90 nm CMOS. , 2008, , .  |     | 8         |
| 77 | A 1.7-GHz 1.5-mW digitally-controlled FBAR oscillator with 0.03-ppb resolution. , 2008, , .  |     | 8         |
| 78 | Characterization of On-Chip Multiport Inductors for Small-Area RF Circuits. IEEE Transactions on Circuits and Systems I: Regular Papers, 2009, 56, 1590-1597.                                    | 5.4 | 8         |
| 79 | A Novel Direct Injection-Locked QPSK Modulator Based on Ring VCO in 180 nm CMOS. IEEE Microwave and Wireless Components Letters, 2014, 24, 269-271.  | 3.2 | 8         |
| 80 | Sample size effect on micro-mechanical properties of gold electroplated with dense carbon dioxide. Surface and Coatings Technology, 2018, 350, 1065-1070.  | 4.8 | 8         |
| 81 | Layout-Aware Compact Model of MOSFET Characteristics Variations Induced by STI Stress. IEICE Transactions on Electronics, 2008, E91-C, 1142-1150.  | 0.6 | 8         |
| 82 | S-Parameter-Based Modal Decomposition of Multiconductor Transmission Lines and Its Application to De-Embedding. , 2009, , .  |     | 7         |
| 83 | A capacitive CMOSâ€MEMS sensor designed by multi-physics simulation for integrated CMOSâ€MEMS technology. Japanese Journal of Applied Physics, 2014, 53, 04EE15.                                 | 1.5 | 7         |
| 84 | Planarized Deposition of High-Quality Silicon Dioxide Film by Photoassisted Plasma CVD at 300Â°C Using Tetraethyl Orthosilicate. Japanese Journal of Applied Physics, 1990, 29, L2341-L2344.     | 1.5 | 6         |
| 85 | Silicon dioxide film deposited by photoassisted microwave plasma CVD using TEOS. Applied Surface Science, 1994, 79-80, 327-331.  | 6.1 | 6         |
| 86 | Inductance-Tuned LC-VCO for Reconfigurable RF Circuit Design. IEICE Electronics Express, 2004, 1, 156-159.   | 0.8 | 6         |
| 87 | Physical design challenges to nano-CMOS circuits. IEICE Electronics Express, 2009, 6, 703-720.   | 0.8 | 6         |
| 88 | Brittle Fracture of Electrodeposited Gold Observed by Micro-Compression. Materials Transactions, 2016, 57, 1257-1260.  | 1.2 | 6         |
| 89 | A â€244-dB FOM High-Frequency Piezoelectric Resonator-Based Cascaded Fractional-N PLL With Sub-ppb-Order Channel-Adjusting Technique. IEEE Journal of Solid-State Circuits, 2017, 52, 1123-1133. | 5.4 | 6         |
| 90 | Nanoscale Hierarchical Structure of Twins in Nanograins Embedded with Twins and the Strengthening Effect. Metals, 2019, 9, 987.  | 2.3 | 6         |

| #   | ARTICLE   | IF  | CITATIONS |
|-----|---|-----|-----------|
| 91  | Planar Solenoidal Inductor in Radio Frequency Micro-Electro-Mechanical Systems Technology for Variable Inductor with Wide Tunable Range and High Quality Factor. Japanese Journal of Applied Physics, 2012, 51, 05EE02. | 1.5 | 6         |
| 92  | Single Crystallization of Aluminum on SiO <sub>2</sub> by Thermal Annealing and Observation with Scanning $\hat{\mu}$ -RHEED Microscope. Japanese Journal of Applied Physics, 1991, 30, L56-L59.                        | 1.5 | 5         |
| 93  | Reliability of Single Electron Transistor Circuits Based on Eb/N0-Bit Error Rate Characteristics. Japanese Journal of Applied Physics, 1999, 38, 403-405.   | 1.5 | 5         |
| 94  | A MOS Transistor-Array for Accurate Measurement of Subthreshold Leakage Variation. , 2007, , .  |     | 5         |
| 95  | An 8.9mW 25Gb/s inductorless 1:4 DEMUX in 90nm CMOS. , 2009, , .  |     | 5         |
| 96  | Radio Frequency Micro Electro Mechanical Systems Inductor Configurations for Achieving Large Inductance Variations and HighQ-factors. Japanese Journal of Applied Physics, 2010, 49, 05FG02.                            | 1.5 | 5         |
| 97  | An 8 channel, 20 V output CMOS switching driver with 3.3 V power supply using triple-well biasing techniques for integrated MEMS device control. Japanese Journal of Applied Physics, 2014, 53, 04EE13.                 | 1.5 | 5         |
| 98  | A 0.5-V 5.8-GHz ultra-low-power RF transceiver for wireless sensor network in 65nm CMOS. , 2014, , .  |     | 5         |
| 99  | A sub-1G CMOS-MEMS accelerometer. , 2015, , .   |     | 5         |
| 100 | Enhancement in structure stability of gold micro-cantilever by constrained fixed-end in MEMS devices. Microelectronic Engineering, 2018, 187-188, 105-109.  | 2.4 | 5         |
| 101 | Sample geometry effect on mechanical property of gold micro-cantilevers by micro-bending test. MRS Communications, 2020, 10, 434-438.   | 1.8 | 5         |
| 102 | Development of Scanning $\hat{\mu}$ -RHEED Microscopy for Imaging Polycrystal Grain Structure in LSI. Japanese Journal of Applied Physics, 1989, 28, 2075-2077.   | 1.5 | 5         |
| 103 | Variable RF Inductor on Si CMOS Chip. , 2003, , .   |     | 5         |
| 104 | Reconfigurable RF CMOS Circuit for Cognitive Radio. IEICE Transactions on Communications, 2008, E91-B, 10-13.   | 0.7 | 5         |
| 105 | Evaluation of LaB <sub>6</sub> Thin Film as Low-Work-Function Gate for MOSFET Operated at Low Temperature. Japanese Journal of Applied Physics, 1990, 29, L1594-L1596.  | 1.5 | 4         |
| 106 | Novel Low-Power Switched-Current Matched Filter for Direct-Sequence Code-Division-Multiple-Access Wireless Communication. Japanese Journal of Applied Physics, 2000, 39, 2301-2304.                                     | 1.5 | 4         |
| 107 | Derivation of interconnect length distribution in X architecture LSIs. , 0, , .   |     | 4         |
| 108 | A 8-Gbps Low-Latency Multi-Drop On-Chip Transmission Line Interconnect with 1.2-mW Two-Way Transceivers. , 2007, , .  |     | 4         |

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|-----|---|-----|-----------|
| 109 | An 8Gbps 2.5mW on-chip pulsed-current-mode transmission line interconnect with a stacked-switch Tx. , 2008, , .   |     | 4         |
| 110 | A MOS transistor array with pico-ampere order precision for accurate characterization of leakage current variation. , 2008, , .   |     | 4         |
| 111 | A Study of Digitally Controllable Radio Frequency Micro Electro Mechanical Systems Inductor. Japanese Journal of Applied Physics, 2011, 50, 05EE01.   | 1.5 | 4         |
| 112 | Planar Solenoidal Inductor in Radio Frequency Micro-Electro-Mechanical Systems Technology for Variable Inductor with Wide Tunable Range and High Quality Factor. Japanese Journal of Applied Physics, 2012, 51, 05EE02. | 1.5 | 4         |
| 113 | A 0.5-V 2.5-GHz high-gain low-power regenerative amplifier based on Colpitts oscillator topology in 65-nm CMOS. , 2014, , .   |     | 4         |
| 114 | An RF energy harvesting power management circuit for appropriate duty-cycled operation. Japanese Journal of Applied Physics, 2015, 54, 04DE11.  | 1.5 | 4         |
| 115 | 0.5 V 5.8 GHz highly linear current-reuse voltage-controlled oscillator with back-gate tuning technique. Japanese Journal of Applied Physics, 2015, 54, 04DE06.   | 1.5 | 4         |
| 116 | E-band filters based on substrate integrated waveguide octagonal cavities loaded by complementary split-ring resonators. , 2015, , .  |     | 4         |
| 117 | Deformation behavior of electroplated gold composed of nano-columnar grains embedded in micro-columnar textures. Materials Letters, 2017, 202, 82-85.   | 2.6 | 4         |
| 118 | Particle Counting in Semiconductor Processing Gas and Apparatus with a New Flow-Cell-Type Laser Particle Counter. Japanese Journal of Applied Physics, 1990, 29, L2405-L2407.   | 1.5 | 3         |
| 119 | In-Situ Counting of Process-Induced Particles. Japanese Journal of Applied Physics, 1992, 31, 918-920.  | 1.5 | 3         |
| 120 | Short-channel-effect free 0.18 /spl mu/m MOSFET by temperature-dimension combination scaling theory: design and experiment. IEEE Electron Device Letters, 1994, 15, 202-205.  | 3.9 | 3         |
| 121 | ULSI interconnect length distribution model considering core utilization. , 0, , .  |     | 3         |
| 122 | Differential transmission line structure for over 10 Gbps signal transmission at global interconnect in Si ULSI. , 0, , .   |     | 3         |
| 123 | On-chip high-Q solenoid inductors embedded in WL-CSP. , 0, , .  |     | 3         |
| 124 | Small-Area Inductor for Silicon CMOS Chips. Japanese Journal of Applied Physics, 2005, 44, 2766-2769.   | 1.5 | 3         |
| 125 | Evaluation of on-chip transmission line interconnect using wire length distribution. , 2005, , .  |     | 3         |
| 126 | Twisted Differential Transmission Line Structure for Global Interconnect in Si LSI. Japanese Journal of Applied Physics, 2005, 44, 2774-2779.   | 1.5 | 3         |



| #   | ARTICLE  | IF  | CITATIONS |
|-----|--|-----|-----------|
| 127 | A Loss Optimization Method Using WD Product for On-Chip Differential Transmission Line Design. , 2006, , .   |     | 3         |
| 128 | A Low-Power Low-Phase-Noise CMOS VCO using RF SiP Technology. , 2007, , .  |     | 3         |
| 129 | A Wideband CMOS LC-VCO Using Variable Inductor. , 2007, , .  |     | 3         |
| 130 | On-chip differential and common mode voltage measurement using off-chip referenced twin probing. , 2008, , .   |     | 3         |
| 131 | Accurate parasitic inductance determination of a ceramic capacitor through 2-port measurements. , 2008, , .  |     | 3         |
| 132 | A low phase noise LC-VCO with a high-Q inductor fabricated by wafer level package technology. , 2008, , .  |     | 3         |
| 133 | Substrate-geometry aware 2-port modeling for surface-mount passive components. , 2008, , .   |     | 3         |
| 134 | A 21 V output charge pump circuit with appropriate well-bias supply technique in 0.18 $\mu\text{m}$ Si CMOS. , 2011, , .   |     | 3         |
| 135 | A dual-axis MEMS inertial sensor using multi-layered high-density metal for an arrayed CMOS-MEMS accelerometer. , 2014, , .  |     | 3         |
| 136 | A design of spring constant arranged for MEMS accelerometer by multi-layer metal technology. , 2016, , .   |     | 3         |
| 137 | A damping constant model for proof-mass structure design of MEMS inertial sensor by multi-layer metal technology. , 2016, , .  |     | 3         |
| 138 | Evaluation and modeling of adhesion layer in shock-protection structure for MEMS accelerometer. Microelectronics Reliability, 2016, 66, 78-84.                                   | 1.7 | 3         |
| 139 | Long-term structure stability of Ti/Au layered micro-cantilever evaluated by vibration test. Microelectronic Engineering, 2019, 207, 33-36.                                      | 2.4 | 3         |
| 140 | Cu-alloying effect on structure stability of electrodeposited gold-based micro-cantilever evaluated by long-term vibration test. Microelectronic Engineering, 2019, 215, 111001. | 2.4 | 3         |
| 141 | Strengthening of micro-cantilever by Au/Ti bi-layered structure evaluated by micro-bending test toward MEMS devices. Microelectronic Engineering, 2019, 213, 13-17.              | 2.4 | 3         |
| 142 | High-Sensitivity Inertial Sensor Module to Measure Hidden Micro Muscular Sounds. , 2019, , .   |     | 3         |
| 143 | An Evaluation Method of Brownian Noise in Highly Sensitive Capacitive Sensors. IEEJ Transactions on Sensors and Micromachines, 2015, 135, 142-143.                               | 0.1 | 3         |
| 144 | A Study of Digitally Controllable Radio Frequency Micro Electro Mechanical Systems Inductor. Japanese Journal of Applied Physics, 2011, 50, 05EE01.                              | 1.5 | 3         |

| #   | ARTICLE  | IF  | CITATIONS |
|-----|--|-----|-----------|
| 145 | Weakness Identification for Effective Repair of Power Distribution Network. Lecture Notes in Computer Science, 2007, , 222-231.  | 1.3 | 3         |
| 146 | (GaAl)As/GaAs Solar Cellsâ€™ Dopant Study of Zn and Be. Japanese Journal of Applied Physics, 1980, 19, 191.  | 1.5 | 2         |
| 147 | Low-Temperature Metal-Oxide-Semiconductor Field-Effect Transistor Operation by Temperature Scaling Theory. Japanese Journal of Applied Physics, 1993, 32, 419-422.   | 1.5 | 2         |
| 148 | High-Rate Deposition of High-Quality Silicon Nitride Film at Room Temperature by Quasi-Remote Plasma Chemical Vapor Deposition. Japanese Journal of Applied Physics, 1995, 34, 6824-6826.                                | 1.5 | 2         |
| 149 | High speed and low power on-chip micro network circuit with differential transmission line. , 0, , .   |     | 2         |
| 150 | Prediction of delay time for future LSI using on-chip transmission line interconnects. , 2005, , .   |     | 2         |
| 151 | Wire Length Distribution Model Considering Core Utilization for System on Chip. , 0, , .   |     | 2         |
| 152 | Zero-Crosstalk Bus Line Structure for Global Interconnects in Si Ultra Large Scale Integration. Japanese Journal of Applied Physics, 2006, 45, 4977-4981.  | 1.5 | 2         |
| 153 | Adaptable wire-length distribution with tunable occupation probability. , 2007, , .  |     | 2         |
| 154 | A Multi-Drop Transmission-Line Interconnect in Si LSI. , 2007, , .   |     | 2         |
| 155 | Small-Area CMOS RF Distributed Mixer Using Multi-Port Inductors. , 2007, , .   |     | 2         |
| 156 | One-Chip Integration of Rapid Diagnosis Infectious-Disease Chip Based on New Phenomena of DNA Trap and Denature in Nanogaps. Japanese Journal of Applied Physics, 2008, 47, 3214-3219.                                   | 1.5 | 2         |
| 157 | Linear Time Calculation of On-Chip Power Distribution Network Capacitance Considering State-Dependence. IEICE Transactions on Fundamentals of Electronics, Communications and Computer Sciences, 2010, E93-A, 2409-2416. | 0.3 | 2         |
| 158 | Linear time calculation of state-dependent power distribution network capacitance. , 2010, , .   |     | 2         |
| 159 | High Strength Electrodeposited Au-Cu Alloys Evaluated by Bending Test toward Movable Micro-Components. ECS Journal of Solid State Science and Technology, 2019, 8, P412-P415.  | 1.8 | 2         |
| 160 | Alloy Electroplating and Youngâ€™s Modulus Characterization of AuCu Alloy Microcantilevers. Journal of the Electrochemical Society, 2020, 167, 082503.   | 2.9 | 2         |
| 161 | Effective Youngâ€™s Modulus of Complex Three Dimensional Multilayered Ti/Au Micro-Cantilevers Fabricated by Electrodeposition and the Temperature Dependency. Electrochem, 2021, 2, 216-223.                             | 3.3 | 2         |
| 162 | Wire Length Distribution Model for System LSI. IEICE Transactions on Fundamentals of Electronics, Communications and Computer Sciences, 2005, E88-A, 3445-3452.  | 0.3 | 2         |

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|-----|--|-----|-----------|
| 163 | An Evaluation Method of the Number of Monte Carlo STA Trials for Statistical Path Delay Analysis. IEICE Transactions on Fundamentals of Electronics, Communications and Computer Sciences, 2008, E91-A, 957-964. | 0.3 | 2         |
| 164 | Effect of current density on micro-mechanical property of electrodeposited gold film evaluated by micro-compression. Surface and Coatings Technology, 2022, 436, 128315.   | 4.8 | 2         |
| 165 | Effects of Hydrogen Terminated Substrate Surface on Succeeding Selective Deposition. Materials Research Society Symposia Proceedings, 1993, 315, 59.   | 0.1 | 1         |
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